

TO-220

Pin Definition:

1. Gate
2. Drain
3. Source

PRODUCT SUMMARY

V_{DS} (V)	$R_{DS(on)}$ (Ω)	I_D (A)
500	1.8 @ $V_{GS} = 10V$	2.2

General Description

The TSM5N50 N-Channel enhancement mode Power MOSFET is produced by planar stripe DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switch mode power supply, power factor correction, electronic lamp ballast based on half bridge.

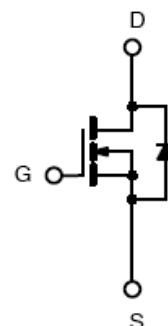
Features

- Low gate charge typical @ 13nC
- Low Crss typical @ 8.5pF
- Fast Switching
- 100% avalanche tested
- Improved dv/dt capability

Ordering Information

Part No.	Package	Packing
TSM5N50CZ C0	TO-220	50pcs / Tube

Block Diagram


N-Channel MOSFET

Absolute Maximum Rating ($T_a = 25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	500	V
Gate-Source Voltage	V_{GS}	± 30	V
Continuous Drain Current	I_D	4.5	A
Pulsed Drain Current	I_{DM}	18	A
Continuous Source Current (Diode Conduction)	I_S	4.5	A
Peak Diode Recovery (Note 2)	dv/dt	4.5	V/ns
Single Pulse Drain to Source Avalanche Energy (Note 3)	EAS	300	mJ
Maximum Power Dissipation @ $T_a = 25^\circ C$	P_D	85	W
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 to +150	$^\circ C$

Thermal Performance

Parameter	Symbol	Limit	Unit
Thermal Resistance - Junction to Case	$R_{\theta JC}$	1.47	$^\circ C/W$
Thermal Resistance - Junction to Ambient	$R_{\theta JA}$	62.5	$^\circ C/W$

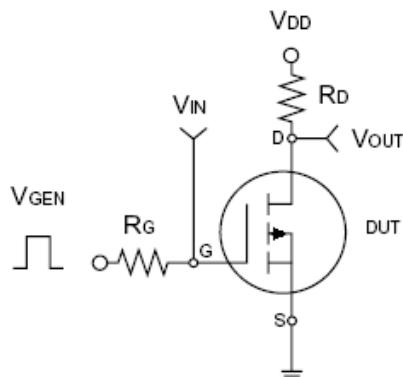
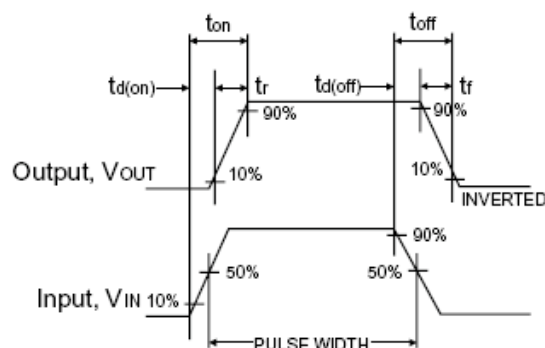
Notes: Surface mounted on FR4 board $t \leq 10sec$

Electrical Specifications (Ta = 25°C unless otherwise noted)

Parameter	Conditions	Symbol	Min	Typ	Max	Unit
Static						
Drain-Source Breakdown Voltage	V _{GS} = 0V, I _D = 250uA	BV _{DSS}	500	--	--	V
Drain-Source On-State Resistance	V _{GS} = 10V, I _D = 2.2A	R _{DS(ON)}	--	1.36	1.8	Ω
Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = 250uA	V _{GS(TH)}	3.0	--	5.0	V
Zero Gate Voltage Drain Current	V _{DS} = 500V, V _{GS} = 0V	I _{DSS}	--	--	1	uA
Gate Body Leakage	V _{GS} = ±30V, V _{DS} = 0V	I _{GSS}	--	--	±100	nA
Forward Transconductance	V _{DS} = 50V, I _D = 2.2A	g _{fs}	--	4	--	S
Diode Forward Voltage	I _S = 4.5A, V _{GS} = 0V	V _{SD}	--	--	1.4	V
Dynamic^b						
Total Gate Charge	V _{DS} = 250V, I _D = 4.5A, V _{GS} = 10V	Q _g	--	13	17	nC
Gate-Source Charge		Q _{gs}	--	3.4	--	
Gate-Drain Charge		Q _{gd}	--	6.4	--	
Input Capacitance	V _{DS} = 25V, V _{GS} = 0V, f = 1.0MHz	C _{iss}	--	470	610	pF
Output Capacitance		C _{oss}	--	75	95	
Reverse Transfer Capacitance		C _{rss}	--	8.5	11	
Switching^c						
Turn-On Delay Time	V _{GS} = 10V, I _D = 4.5A, V _{DD} = 250V, R _G = 25Ω	t _{d(on)}	--	13	35	nS
Turn-On Rise Time		t _r	--	55	120	
Turn-Off Delay Time		t _{d(off)}	--	25	60	
Turn-Off Fall Time		t _f	--	35	80	
Reverse Recovery Time	V _{GS} = 0V, I _S = 4.5A, di _f /dt = 100A/us	t _{fr}	--	215	--	uS
Reverse Recovery Charge		Q _{rr}	--	1.26	--	

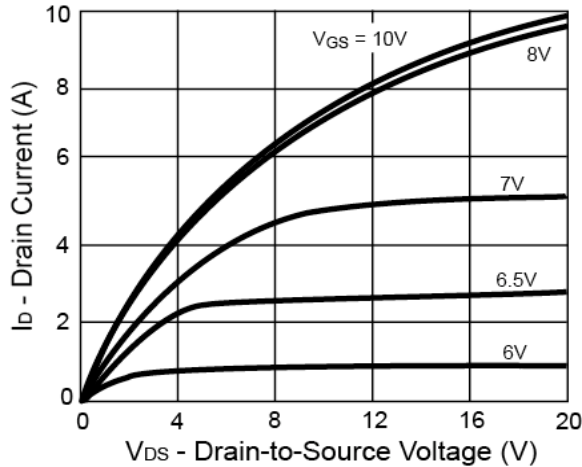
Notes:

1. Pulse test: pulse width ≤300uS, duty cycle ≤2%
2. I_{SD} < 4.5A, di/dt < 200A/us, V_{DD} < BV_{DSS}
3. V_{DD} = 50V, V_{GS} = 10V, I_{AS} = 4.5A, L = 27mH, R_G = 25Ω
4. For design reference only, not subject to production testing.
5. Switching time is essentially independent of operating temperature.

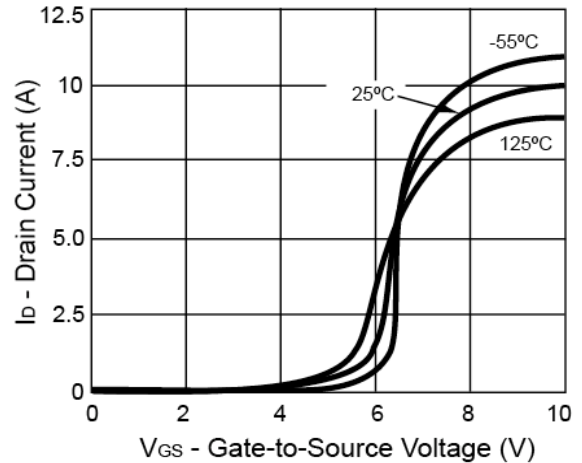

Switching Test Circuit

Switchin Waveforms

Electrical Characteristics Curve ($T_a = 25^\circ\text{C}$, unless otherwise noted)

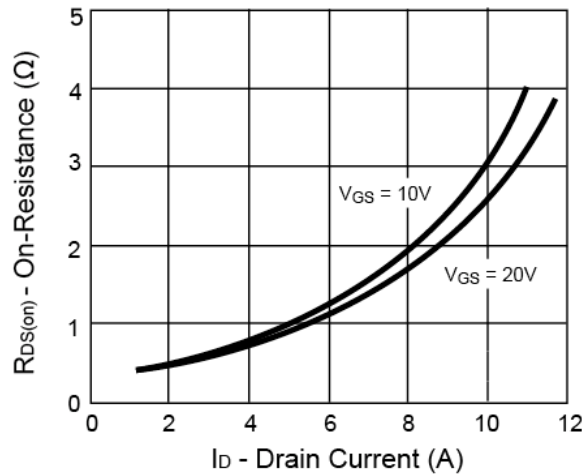
Output Characteristics



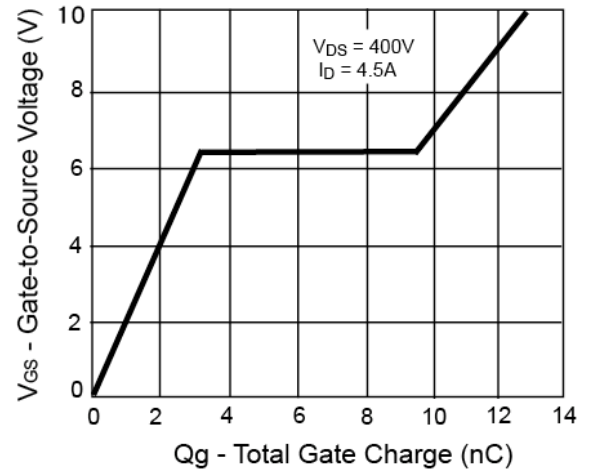
Transfer Characteristics



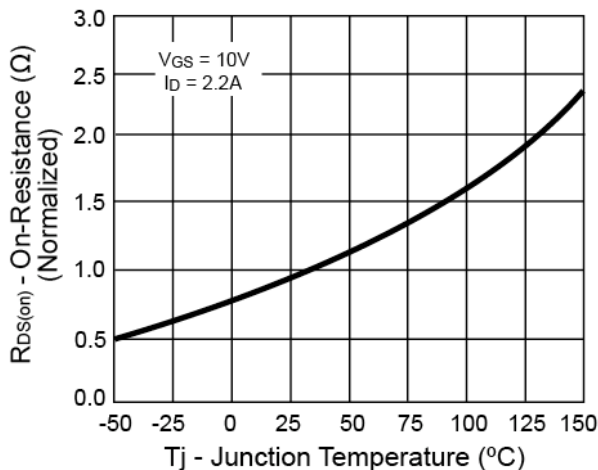
On-Resistance vs. Drain Current



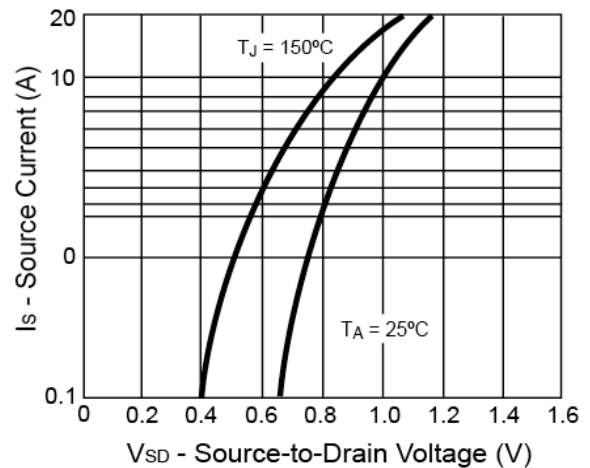
Gate Charge



On-Resistance vs. Junction Temperature

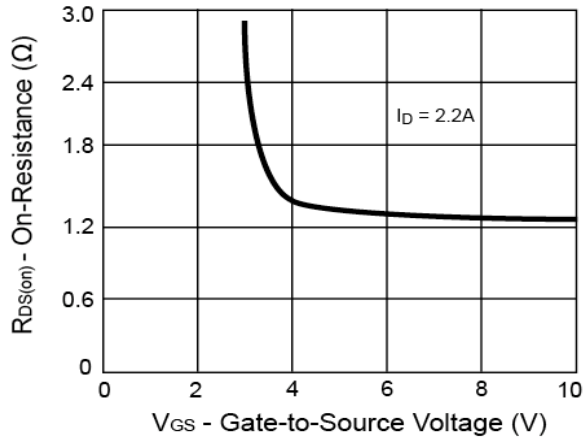


Source-Drain Diode Forward Voltage

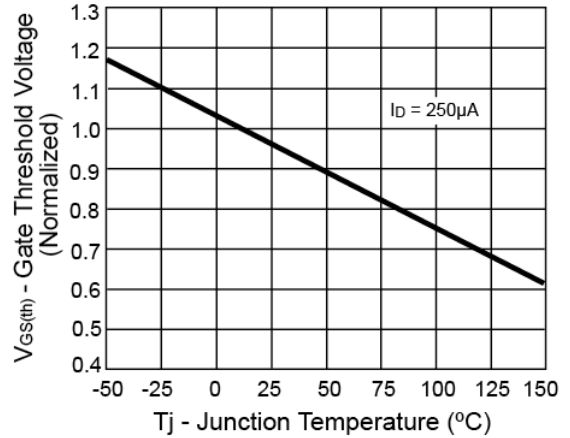


Electrical Characteristics Curve ($T_a = 25^\circ\text{C}$, unless otherwise noted)

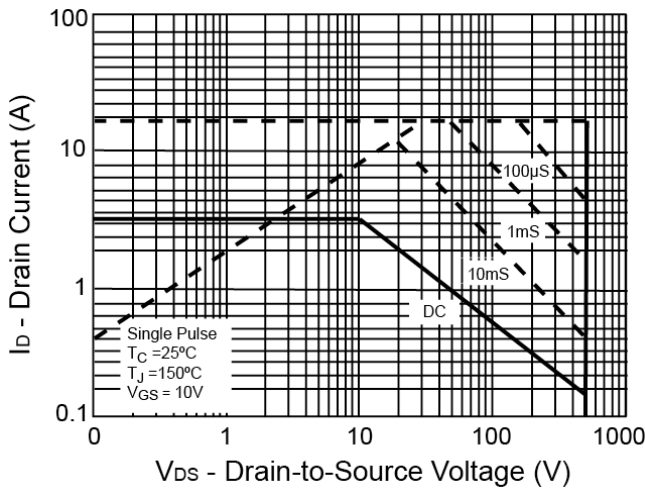
On-Resistance vs. Gate-Source Voltage



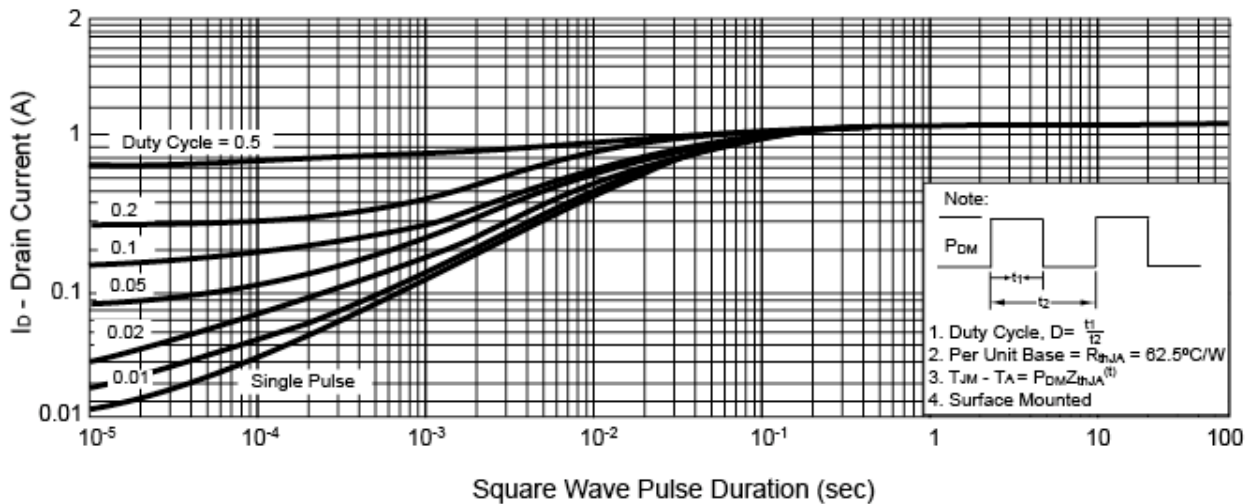
Threshold Voltage



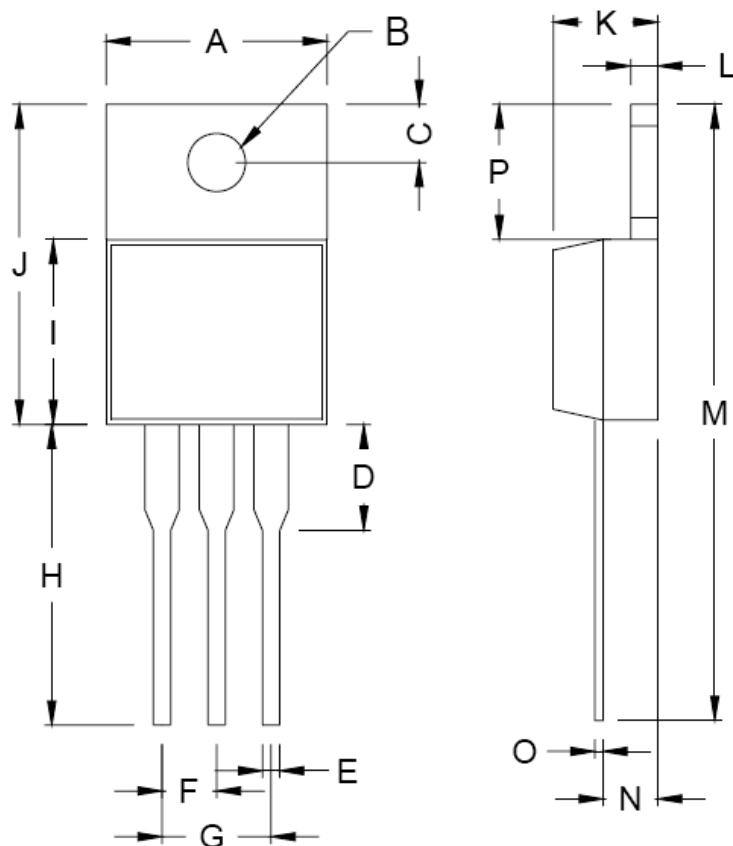
Maximum Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Ambient

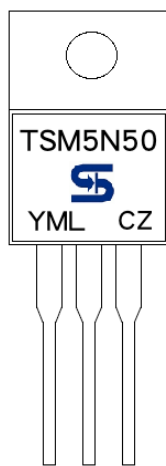


TO-220 Mechanical Drawing



TO-220 DIMENSION				
DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	10.000	10.500	0.394	0.413
B	3.740	3.910	0.147	0.154
C	2.440	2.940	0.096	0.116
D	-	6.350	-	0.250
E	0.381	1.106	0.015	0.040
F	2.345	2.715	0.092	0.058
G	4.690	5.430	0.092	0.107
H	12.700	14.732	0.500	0.581
J	14.224	16.510	0.560	0.650
K	3.556	4.826	0.140	0.190
L	0.508	1.397	0.020	0.055
M	27.700	29.620	1.060	1.230
N	2.032	2.921	0.080	0.115
O	0.255	0.610	0.010	0.024
P	5.842	6.858	0.230	0.270

Marking Diagram



- Y** = Year Code
- M** = Month Code
(A=Jan, B=Feb, C=Mar, D=Apr, E=May, F=Jun, G=Jul, H=Aug, I=Sep, J=Oct, K=Nov, L=Dec)
- L** = Lot Code

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